

**Harmonized system of quality
assessment for electronic components:**

Capability detail specification: Flexible printed boards without through-connections

The European Standard EN 123400-800:1992 has the status of a
British Standard

Committees responsible for this British Standard

The preparation of this British Standard was entrusted by the Electronic Components Standards Policy Committee (ECL/-) to Technical Committee ECL/19, upon which the following bodies were represented:

- British Telecommunications plc
- EEA (The Association of the Electronics, Telecommunications and Business Equipment Industries)
- Electrical and Electronic Insulation Association (BEAMA Ltd.)
- Electronic Components Industry Federation
- Electronic Engineering Association
- ERA Technology Ltd.
- GAMBICA (BEAMA Ltd.)
- Ministry of Defence
- National Supervising Inspectorate
- Printed Circuit Interconnection Federation

This British Standard, having been prepared under the direction of the Electronic Components Standards Policy Committee, was published under the authority of the Standards Board and comes into effect on 20 December 1991

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The following BSI references relate to the work on this standard:
Committee reference ECL/19
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Amendments issued since publication

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National foreword

This British Standard has been prepared under the direction of the Electronics Components Standards Policy Committee. It is identical with CENELEC Electronic Components Committee (CECC) 23400-800:1990 “*Harmonized system of quality assessment for electronic components: Capability detail specification: Flexible printed boards without through-connections*”.

This standard is a harmonized specification within the CECC system and should be read in conjunction with BS CECC 23000 and BS CECC 23400.

In 1992 the CENELEC Electronic Components Committee (CECC) accepted CECC 23400-800:1990 as European Standard EN 123400-800:1992.

Cross-references

The British Standard which implements CECC 00100 is BS 9000, “*General requirements for a system for electronic components of assessed quality*”, Part 2:1991 “*Specification for the national implementation of the CECC system*”.

International Standard	Corresponding British Standard
CECC 23000:1985	BS CECC 23000:1989 <i>Harmonized system of quality assessment for electronic components: Generic specification: Printed boards</i> (Identical)
CECC 23400:1985	BS CECC 23400:1990 <i>Specification for harmonized system of quality assessment for electronic components: Sectional specification: Flexible printed boards without through-connections</i> (Identical)
IEC 68	BS 2011 <i>Environmental testing</i> (Most Parts are identical)
IEC 249	BS 4584 <i>Metal-clad base materials for printed wiring boards</i> (Most Parts are identical) BS 6221 <i>Printed wiring boards</i>
IEC 326-2:1990	Part 2:1991 <i>Methods of test</i> (Identical)
IEC 326-3:1991	Part 3:1991 <i>Guide for the design and use of printed wiring boards</i> (Identical)

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

Compliance with a British Standard does not of itself confer immunity from legal obligations.

Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the EN title page, page 2, the CECC title page, pages ii to iv, pages 1 to 6 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

UDC:

Descriptors: Quality, electronic components, printed boards

English version

Capability Detail Specification: Flexible printed boards without through connections

Spécification Particulière d'Agrément: Cartes
imprimées souples sans connexions
transversales

Bauartspezifikation zur Anerkennung der
Befähigung: Flexible Leiterplatten ohne
Durchverbindungen

This European Standard was approved by the CENELEC Electronic Components Committee (CECC) on 12 December 1991. The text of this standard consists of the text of CECC 23400-800 Issue 1 1990 of the corresponding CECC Specification. CENELEC members are bound to comply with CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the General Secretariat of the CECC or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CECC General Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom. The membership of the CECC is identical, with the exception of the national electrotechnical committees of Greece, Iceland and Luxembourg.

CECC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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